

**Listing of Claims:**

This listing of claims will replace all prior versions, and listing, of claims in the application:

Claim 1 (previously presented): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit

components;

depositing a crossover circuit trace of uniform composition over the sacrificial material, the crossover circuit trace i) conforming to the sacrificial material, and ii) crossing over the circuit components; and

thermally decomposing the sacrificial material.

Claim 2 (withdrawn): The air bridge of claim 1, wherein depositing a sacrificial material comprises depositing the sacrificial material in a manner causing the sacrificial material to be dome shaped.

Claim 3 (original): The air bridge of claim 1, wherein the sacrificial material comprises polynorbornene.

Claim 4 (original): The air bridge of claim 1, wherein the one or more circuit components comprise a circuit trace.

Claim 5 (original): The air bridge of claim 4, wherein the circuit trace comprises a signal trace.

Claim 6 (original): The air bridge of claim 4, wherein the circuit trace comprises a ground trace.

Claim 7 (original): The air bridge of claim 4, wherein the circuit trace comprises a power trace.

Claim 8 (original): The air bridge of claim 1, wherein the crossover circuit trace comprises a signal trace.

Claims 9 – 20 (canceled)

Claim 21 (previously presented): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit components;

depositing a crossover circuit trace of uniform composition over the sacrificial material, the crossover circuit trace i) conforming to the sacrificial material, ii) crossing over the circuit components, and iii) being directly supported by the substrate on opposite sides of the sacrificial material; and

thermally decomposing the sacrificial material.

Claim 22 (withdrawn): The air bridge of claim 21, wherein depositing a sacrificial material comprises depositing the sacrificial material in a manner causing the sacrificial material to be dome shaped.

Claim 23 (previously presented): The air bridge of claim 21, wherein the sacrificial material comprises polynorbornene.

Claim 24 (previously presented): The air bridge of claim 21, wherein the one or more circuit components comprise a circuit trace.

Claim 25 (previously presented): The air bridge of claim 24, wherein the circuit trace comprises a signal trace.

Claim 26 (previously presented): The air bridge of claim 24, wherein the circuit trace comprises a ground trace.

Claim 27 (previously presented): The air bridge of claim 24, wherein the circuit trace comprises a power trace.

Claim 28 (previously presented): The air bridge of claim 21, wherein the crossover circuit trace comprises a signal trace.